MAZMxxxH Series

Silicon planar type

For surge absorption circuit

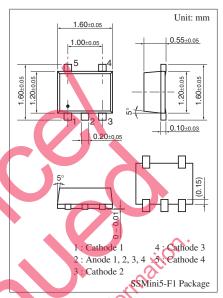
■ Features

- Four elements anode-common type
- Power dissipation P_D: 150 mW

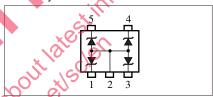
■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter	Symbol	Rating	Unit
Power dissipation *	P_{D}	150	mW
Junction temperature	T_{j}	150	°C
Storage temperature	T_{stg}	-55 to +150	°C

Note) *: $P_D = 150$ mW achieved with a printed circuit board.



Internally connected circuit



■ Common Electrical Characteristics $T_a = 25$ °C ± 3 °C

Parameter	Symbol	Conditions	Min Typ	Max	Unit
Zener voltage *	Vz	I _Z Specified value —			V
Zener rise operating resistance R _{ZK} I _Z Specified value Refer to the list of the					Ω
Zener operating resistance	R_{Z}	YT (C' 1 1	hin part numbers		Ω
Reverse current	I_R	V _R Specified value			μΑ

- Note) 1. Measuring methods are based JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.
 - 2. Electrostatic breakdown voltage is ±10 kV

Test method: IEC1000-4-2 (C=150 pF, R = 330 Ω , Contact discharge: 10 times)

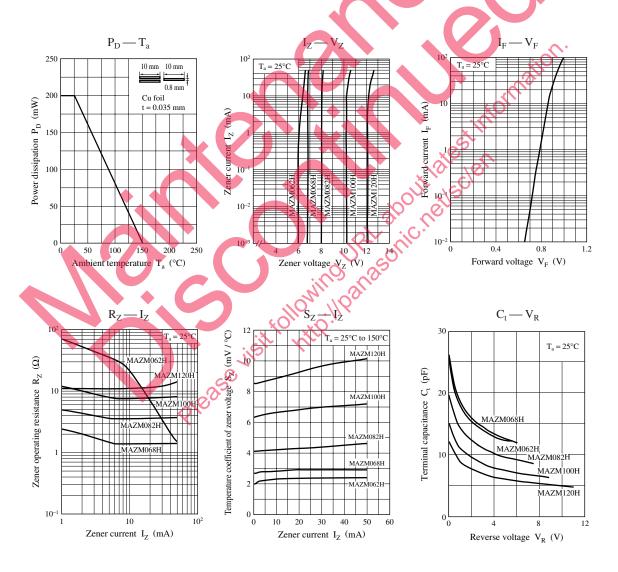
3. *: The temperature must be controlled 25°C for V_Z mesurement.

 V_Z value measured at other temperature must be adjusted to $V_Z\,(25^{\circ}\text{C})$

 $\ensuremath{V_{Z}}$ guaranted 20 ms after current flow.

■ Electrical characteristics within part numbers $T_a = 25^{\circ}C \pm 3^{\circ}C$

Part number	Zener voltage $V_Z(V)$			Reverse current (DC) I _R (μA)		Zener operating resistance $R_Z(\Omega)$	Zener rise operating resistance $R_{ZK}(\Omega)$	ng ce	
		1	1	Iz		V_R	-	$I_Z = 0.5 \text{ mA}$	
	Min	Nom	Max	(mA)	Max	(V)	Max	Max	
MAZM062H	5.8	6.2	6.6	5	0.2	4	50	100	6.2Z
MAZM068H	6.4	6.8	7.2	5	0.1	4	30	60	6.8Z
MAZM082H	7.7	8.2	8.7	5	0.1	5	30	60	8.2Z
MAZM100H	9.4	10.0	10.6	5	0.05	7	30	60	10Z
MAZM120H	11.4	12.0	12.7	5	0.05	9	30	80	12Z



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